



100% Material Declaration Data Sheet CSG324

PK386 (v1.1) March 11, 2011

Average Weight: 0.524 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.022310	4.258
	Silicon	7440-21-3	100.00	Basis	0.022310	
Die Attach Material					0.007051	1.346
	Silver	7440-22-4	77.50	Basis	0.005465	
	Bismaleimide monomer	Trade Secret	15.00	Basis	0.001058	
	Acrylate monomer	Trade Secret	7.50	Basis	0.000529	
Mold Compound					0.216190	41.258
	Solid Epoxy Resin	Trade Secret	5.00	Basis	0.010810	
	Phenol Resin	Trade Secret	5.00	Basis	0.010810	
	Fused Silica	60676-86-0	87.45	Basis	0.189058	
	Metal Hydroxide	Trade Secret	2.00	Basis	0.004324	
	Carbon Black	1333-86-4	0.55	Basis	0.001189	
Gold Wire					0.007801	1.489
	Gold	7440-57-5	99.05	Basis	0.007727	
	Palladium	7440-05-3	0.95	Basis	0.000074	
Solder Balls					0.114184	21.791
	Tin	7440-31-5	96.50	Basis	0.110188	
	Silver	7440-22-4	3.00	Basis	0.003426	
	Copper	7440-50-8	0.50	Basis	0.000571	
Substrate					0.156464	29.860
	Copper	7440-50-8	48.13	Basis	0.075300	
	Nickel	7440-02-0	2.94	Basis	0.004598	
	Gold	7440-57-5	0.35	Basis	0.000550	
	BT (core)	21645-51-2/ 7440-50-8/ Epoxy resin	44.31	Basis	0.069324	
	Solder mask	14807-96-6/ 7727-43-7/ 7631-86-9/ 34590-94-8/ 85954-11-6	4.28	Basis	0.006692	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
12/3/10	1.0	Initial Xilinx release.
03/11/11	1.1	Revised component weights based on latest data

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